COMPLIANT



E Series Power MOSFET

PRODUCT SUMMA	RY	
V _{DS} (V) at T _J max.	550)
R _{DS(on)} max. at 25 °C (Ω)	V _{GS} = 10 V	0.243
Q _g max. (nC)	66	
Q _{gs} (nC)	8	
Q _{gd} (nC)	14	
Configuration	Sing	le

Thin-Lead TO-220 FULLPAK G DS N-Channel MOSFET

FEATURES

- Low figure-of-merit (FOM) Ron x Qq
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Low gate charge (Q_a)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishav.com/doc?99912</u>

APPLICATIONS

- Computing
 - PC silver box / ATX power supplies
- Lighting
 - Two stage LED lighting
- Consumer electronics
- Applications using hard switched topologies
 - Power factor correction (PFC)
 - Two switch forward converter
 - Flyback converter
- Switch mode power supplies (SMPS)

ORDERING INFORMATION	
Package	Thin-Lead TO-220 FULLPAK
Lead (Pb)-free	SiHA15N50E-E3

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unl	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V_{DS}	500	V
Gate-Source Voltage		V_{GS}	± 30	V	
Continuous Drain Current (T,I = 150 °C) e	V at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$		14.5	
Continuous Drain Current (1) = 150 C)	V _{GS} at 10 V	T _C = 100 °C	I _D	9.2	Α
Pulsed Drain Current ^a			I _{DM}	28	
Linear Derating Factor				1.25	W/°C
Single Pulse Avalanche Energy b		E _{AS}	136	mJ	
Maximum Power Dissipation			P_{D}	33	W
Operating Junction and Storage Temperature Range	е		T _J , T _{stg}	-55 to +150	°C
Drain-Source Voltage Slope	$V_{DS} = 0 V t$	o 80 % V _{DS}	d\//d#	70	1//20
Reverse Diode dV/dt ^d			dV/dt	27	V/ns
Soldering Recommendations (Peak Temperature) c	for	10 s		300	°C

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 3.1 A.
- c. 1.6 mm from case.
- d. $I_{SD} \le I_D$, $dI/dt = 100 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$.
- e. Limited by maximum junction temperature.

THERMAL RESISTANCE RATI	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	65	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	-	3.8	G/ VV



Vishay Siliconix

SPECIFICATIONS ($T_J = 25$ °C, u	nless otherwi	se noted)					
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static					l .		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$		500	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	-	0.62	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.0	-	4.0	V
Octo Course Legisers			$V_{GS} = \pm 20 \text{ V}$		-	± 100	nA
Gate-Source Leakage	I_{GSS}		$V_{GS} = \pm 30 \text{ V}$	-		± 1	μΑ
Zawa Cata Valtana Dunin Comunat		V _{DS} =	= 500 V, V _{GS} = 0 V	-	-	10	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 400 \	/, V _{GS} = 0 V, T _J = 125 °C	-	-	25	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 7.5 A	-	0.243	0.280	Ω
Forward Transconductance	9fs	V _{DS} = 30 V, I _D = 7.5 A		-	3.9	-	S
Dynamic		•				•	
Input Capacitance	C _{iss}		V _{GS} = 0 V,		1162	-	
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 100 V, f = 1 MHz		-	51	-	pF
Reverse Transfer Capacitance	C _{rss}			-	7	-	
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		-	55	-	
Effective Output Capacitance, Time Related ^b	$C_{o(tr)}$			-	164	-	
Total Gate Charge	Qg			-	33	66	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$I_D = 7.5 \text{ A}, V_{DS} = 400 \text{ V}$	-	8	-	nC
Gate-Drain Charge	Q _{gd}			-	14	-	
Turn-On Delay Time	t _{d(on)}			-	15	30	
Rise Time	t _r	$V_{DD} = 400 \text{ V}, I_{D} = 12 \text{ A}, V_{GS} = 10 \text{ V}, R_{g} = 9.1 \Omega$		-	24	48	ns
Turn-Off Delay Time	t _{d(off)}			-	34	68	
Fall Time	t _f				18	36	
Gate Input Resistance	R _g	f = 1 MHz, open drain		-	0.85	-	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	Is	MOSFET sym showing the	MOSFET symbol showing the		-	14.5	
Pulsed Diode Forward Current	I _{SM}	integral reverse p - n junction diode		-	-	28	- A
Diode Forward Voltage	V _{SD}	T _J = 25 °C	C, I _S = 7.5 A, V _{GS} = 0 V	-	-	1.2	V
Reverse Recovery Time	t _{rr}			-	265	-	ns
Reverse Recovery Charge	Q _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 7.5 \text{ A},$ $dI/dt = 100 \text{ A/}\mu\text{s}, V_B = 25 \text{ V}$		-	3.2	-	μC
Reverse Recovery Current	I _{RRM}	ai/at =	100 AV 48, VR = 23 V	-	23	-	A

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

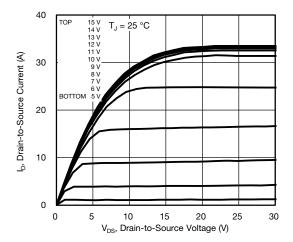


Fig. 1 - Typical Output Characteristics

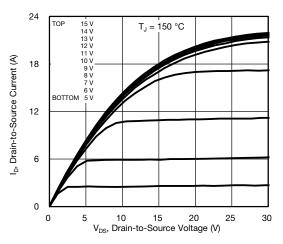


Fig. 2 - Typical Output Characteristics

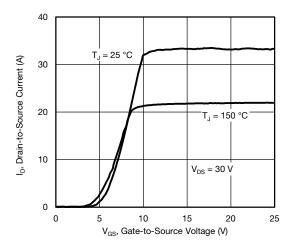


Fig. 3 - Typical Transfer Characteristics

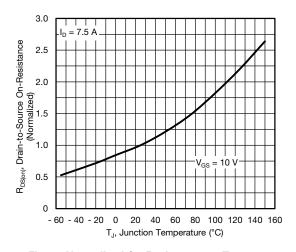


Fig. 4 - Normalized On-Resistance vs. Temperature

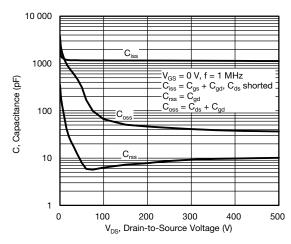


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

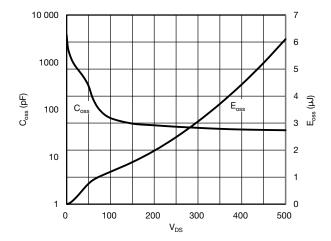


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



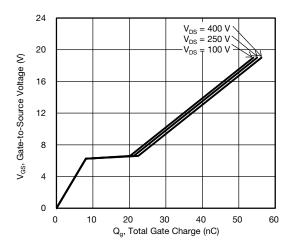


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

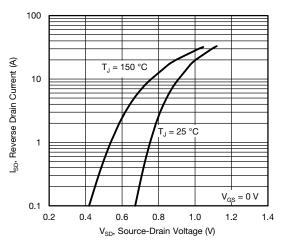


Fig. 8 - Typical Source-Drain Diode Forward Voltage

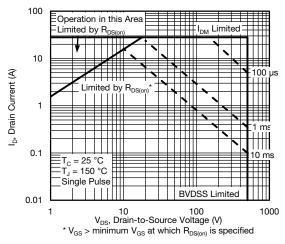


Fig. 9 - Maximum Safe Operating Area

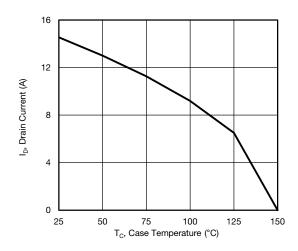


Fig. 10 - Maximum Drain Current vs. Case Temperature

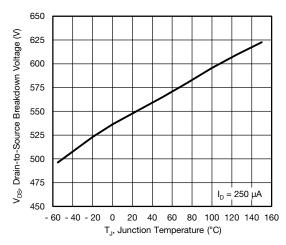


Fig. 11 - Temperature vs. Drain-to-Source Voltage



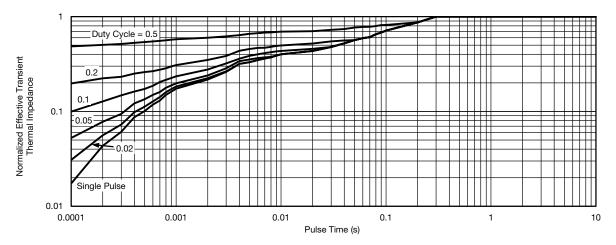


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

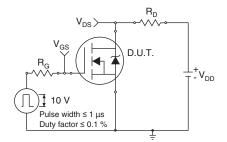


Fig. 13 - Switching Time Test Circuit

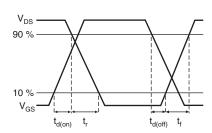


Fig. 14 - Switching Time Waveforms

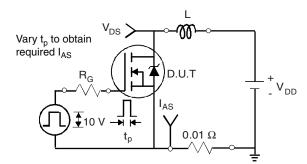


Fig. 15 - Unclamped Inductive Test Circuit

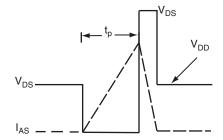


Fig. 16 - Unclamped Inductive Waveforms

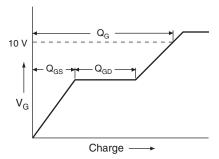


Fig. 17 - Basic Gate Charge Waveform

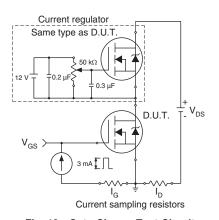
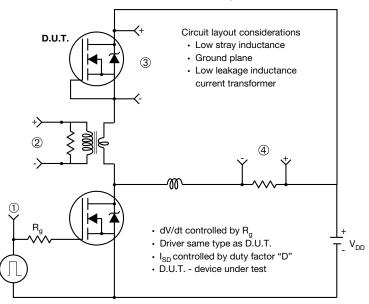


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



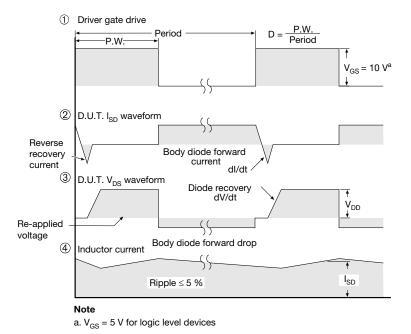


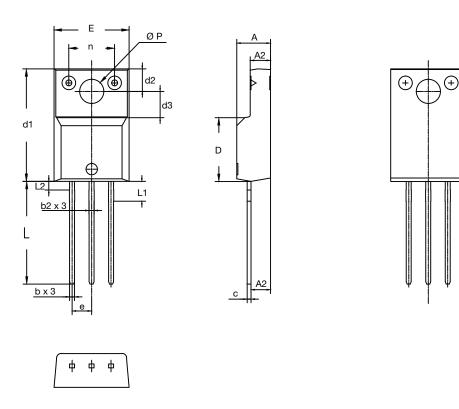
Fig. 19 - For N-Channel

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TO-220 FULLPAK Thin Lead



SYMBOL	DIMENSIONS				
	MILLIN	METERS	INC	HES	
	MIN.	MAX.	MIN.	MAX.	
Α	4.30	4.70	0.169	0.185	
A1	2.50	2.90	0.098	0.114	
A2	2.50	2.70	0.098	0.106	
b	0.60	0.80	0.024	0.031	
b2	0.60	0.90	0.024	0.035	
С	-	0.60	-	0.024	
D	8.30	8.70	0.327	0.342	
d1	14.70	15.30	0.579	0.602	
d2	2.90	3.10	0.114	0.122	
d3	3.40	3.60	0.134	0.142	
Е	9.70	10.30	0.382	0.406	
е	2.50	2.70	0.098	0.106	
L	13.40	13.80	0.528	0.543	
L1	2.50	2.80	0.098	0.110	
L2	-	1.20	-	0.047	
n	6.05	6.15	0.238	0.242	
ØP	3.00	3.40	0.118	0.134	

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